SPECIFICATIONS

Optical & Imaging System

| Top View Camera | 4 Mpx high speed color camera |
|--------------------|-------------------------------|
| Lighting | Multi-phase RGB+W LED |
| Optical Resolution | 10 or 15 μm |
| Imaging Method | Dynamic Imaging |

Imaging/Inspection Speed

| 15 μm | 120 cm ² /sec (18.6 in ² /sec) |
|-------|--|
| 10 μm | 60 cm ² /sec (9.3 in ² /sec) |

Pre-/Post-Reflow Inspection Functions

| Component | Missing, Tombstoning, Billboarding, Polarity, Rotation, Shift, Wrong Marking (OCV), Defective, Upside Down, Extra Component |
|--------------|---|
| Solder Joint | Excess Solder, Insufficient solder, Bridging, Through-hole Pins, |

X-Y Table & Control

Ballscrew + AC servo with motion controller

X-Y Axis Resolution 1 µm

PCB & Conveyor System

| Min. PCB Size | 50 x 50 mm (1.97 x 1.97 in) | | |
|------------------------------------|---|--|--|
| | TR7700 SIII DT | TR7700L SIII DT | |
| Max. PCB Size | 330 x 250 mm (13.0 x 9.84 in) | 510 x 460 mm (20.1 x 18.1 in) | |
| Max. PCB Thickness | 3 mm (0.12 in) | | |
| Max. PCB Weight | 3 kg (6.61 lbs) | | |
| PCB Carrier/Fixing | Motor Driven Clamping | | |
| Clearance Top Bottom Edge | 25 mm (0.98 in) 100 mm (3.94 in) 3 mm (0.12 in) | 25 mm (0.98 in) 50 mm (1.97 in) 3 mm (0.12 in) | |
| Dimensions (W) x (D) x (H) | 800 x 1100 x 1350 mm (31.5 x 43.3 x 53.2 in) | 980 x 1290 x 1400 mm (38.6 x 50.8 x 55.1 in) | |
| Weight | 340 kg (750 lbs) | 385 kg (849 lbs) | |
| Power Requirement | 200 - 240 V, single phase, 50/60 Hz 2 kVA | | |

Options

Barcode Scanner, Repair Station, Offline Editor, OCR, TRI's Yield Management System (YMS), YMS Lite, Support Pin



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C-7700 SIII DT-EN-1405





DESKTOP AUTOMATED OPTICAL INSPECTION

TR7700 SIII DT FEATURES

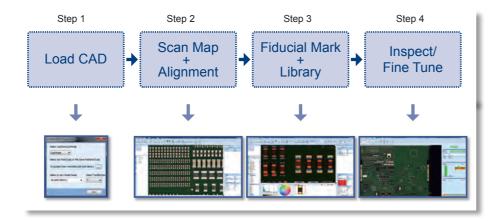
Premium Desktop AOI with World Class Performance

TR7700 SIII DT captures high precision full PCB panel images in unprecedented detail using TRI's exclusive multi-phase lighting. Next generation inspection software combines excellent defect detection and easy programming into a state-of-the-art desktop AOI solution.

Intelligent Easy Programming Interface

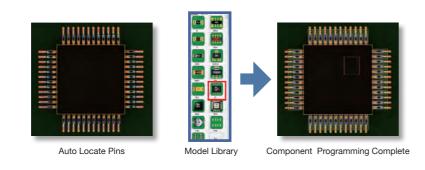
New intelligent programming process significantly reduces programming time using automated component library and integrated board warp compensation.

Programming Flowchart



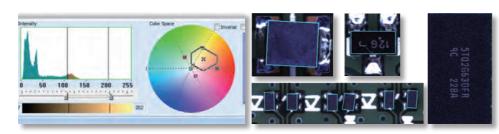
Auto Library + Model Library

Auto Library speeds up programming by automatically allocating inspection windows for IC leads.



New Color Space Algorithms

TRI's new adaptive algorithms use color space processing to increase inspection accuracy, reduce false calls and improve inspection results while reducing time necessary for inspection fine tuning and the number of alternative images required.



Color Differentiation Analysis for Black Resin Parts

High Speed with Multi-phase Lighting

Four individual lighting phases improve inspection of individual defect types using specialized lighting conditions. High speed camera allows inspection at constant speed even with multiple lighting phases.



Flexible multi-board Merging & Speedy Inspection

- Simultaneous access to multiple component information for easy programming.
- Saves multi-fiducial mark scanning time for multi-board programs.

Auto-clamping Conveyor System

Single button PCB loading and unloading reduces operator workload and improves board loading time.

High Speed Ballscrew X-Y Motion Drive

Servo motor with high precision control helps deliver stable and reliable inspection results.

SMT Line Integration

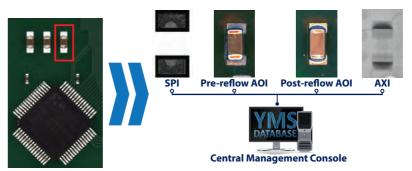
Centralized production line management increases operator productivity and response time. TRI's integrated solution includes the following four components.

• Offline Editor

This application allows for centralized independent adjustment and fine tuning of inspection algorithms on previously scanned images while providing immediate feedback. The completed program can then be uploaded to the in-line inspection machines to improve inspection stability and accuracy.

YMS Lite

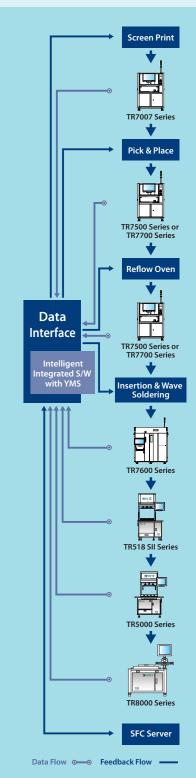
TRI's Yield Management System links inspection data from SPI, AOI and AXI systems to trace defect roots throughout the PCB assembly line. Modular architecture provides centralized inspection management, real time defect monitoring with analysis and defect knowledge management necessary to identify problems and implement solutions to maximize production vields.



Quality Validation

Fully automated collection of good/failed images from a complete production run allows testing, tuning and verification of adjusted program parameters without reloading tested boards. This allows engineers to save inspection time when fine tuning and significantly speeds up New Product Introduction (NPI).

Yield Management System*



- Inspection results and data integration
- Real time SPC and production yield management
- Quality reports and closed loop tracking Support defect component analysis
- and improvements
- Knowledge Management (KM)
- Productivity and Quality Management
 * Optional
 - * Optional

